Quad 2-Input NAND Gate with Open-Drain Outputs High-Performance Silicon-Gate CMOS

The MC74HC03A is identical in pinout to the LS03. The device inputs are compatible with Standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

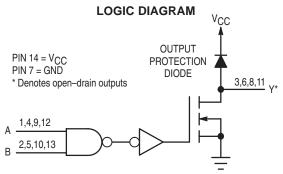
The HC03A NAND gate has, as its outputs, a high–performance MOS N–Channel transistor. This NAND gate can, therefore, with a suitable pullup resistor, be used in wired–AND applications. Having the output characteristic curves given in this data sheet, this device can be used as an LED driver or in any other application that only requires a sinking current.

- Output Drive Capability: 10 LSTTL Loads With Suitable Pullup Resistor
- Outputs Directly Interface to CMOS, NMOS and TTL
- High Noise Immunity Characteristic of CMOS Devices
- Operating Voltage Range: 2 to 6V
- Low Input Current: 1µA
- In Compliance With the JEDEC Standard No. 7A Requirements
- Chip Complexity: 28 FETs or 7 Equivalent Gates

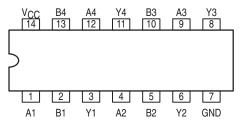
DESIGN GUIDE

Criteria	Value	Unit
Internal Gate Count*	7.0	ea
Internal Gate Propagation Delay	1.5	ns
Internal Gate Power Dissipation	5.0	μW
Speed Power Product	0.0075	рJ

* Equivalent to a two-input NAND gate



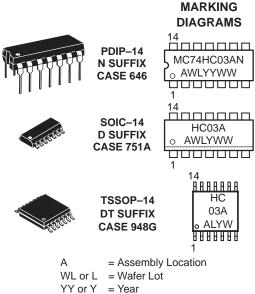
Pinout: 14-Lead Packages (Top View)





ON Semiconductor

http://onsemi.com



WW or W = Work Week

FUNCTION TABLE

Inp	uts	Output
Α	в	Y
L	L	Z
L L	Н	Z
н	L	Z
н	Н	L

Z = High Impedance

ORDERING INFORMATION

Device	Package	Shipping
MC74HC03AN	PDIP-14	2000 / Box
MC74HC03AD	SOIC-14	55 / Rail
MC74HC03ADR2	SOIC-14	2500 / Reel
MC74HC03ADT	TSSOP-14	96 / Rail
MC74HC03ADTR2	TSSOP-14	2500 / Reel

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage (Referenced to GND)	– 0.5 to + 7.0	V
Vin	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
Vout	DC Output Voltage (Referenced to GND)	- 0.5 to V _{CC} + 0.5	V
l _{in}	DC Input Current, per Pin	± 20	mA
l _{out}	DC Output Current, per Pin	± 25	mA
ICC	DC Supply Current, V_{CC} and GND Pins	± 50	mA
PD	Power Dissipation in Still Air Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T _{stg}	Storage Temperature	– 65 to + 150	°C
т∟	Lead Temperature, 1 mm from Case for 10 Seconds Plastic DIP, SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C

SOIC Package: - 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
VCC	DC Supply Voltage (Referenced to GND)			6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)			VCC	V
ТА	Operating Temperature, All Package Types			+ 125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1)	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC CHARACTERISTICS (Voltages Referenced to GND)

			V _{CC}	Guaranteed Limit			
Symbol	Parameter	Condition	Ň	–55 to 25°C	≤85°C	≤125°C	Unit
VIH	Minimum High–Level Input Voltage	$V_{out} = 0.1V \text{ or } V_{CC} - 0.1V$ $ I_{out} \le 20\mu A$	2.0 3.0 4.5 6.0	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	V
VIL	Maximum Low-Level Input Voltage	$V_{out} = 0.1V \text{ or } V_{CC} - 0.1V$ $ I_{out} \le 20\mu A$	2.0 3.0 4.5 6.0	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	V
VOL	Maximum Low–Level Output Voltage	$V_{out} = 0.1V \text{ or } V_{CC} - 0.1V$ $ I_{out} \le 20\mu A$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$ \begin{array}{ll} V_{in} = V_{IH} \text{ or } V_{IL} & I_{out} \leq 2.4 \text{mA} \\ I_{out} \leq 4.0 \text{mA} \\ I_{out} \leq 5.2 \text{mA} \end{array} $	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
l _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μΑ
ICC	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0\mu A$	6.0	1.0	10	40	μΑ
I _{OZ}	Maximum Three–State Leakage Current	Output in High–Impedance State $V_{in} = V_{IL}$ or V_{IH} $V_{out} = V_{CC}$ or GND	6.0	±0.5	±5.0	±10	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

AC CHARACTERISTICS (C_L = 50pF, Input $t_f = t_f = 6ns$)

		V _{CC} Guaranteed Limit		it		
Symbol	Parameter	v	–55 to 25°C	≤85°C	≤125°C	Unit
tpLZ, tpZL	Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 2)	2.0 3.0 4.5 6.0	120 45 24 20	150 60 30 26	180 75 36 31	ns
ttlh, tthL	Maximum Output Transition Time, Any Output (Figures 1 and 2)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 16	110 36 22 19	ns
C _{in}	Maximum Input Capacitance	-	10	10	10	pF
C _{out}	Maximum Three–State Output Capacitance (Output in High–Impedance State)		10	10	10	pF

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V_{CC} = 5.0 V, V_{EE} = 0 V	
C _{PD}	Power Dissipation Capacitance (Per Buffer)*	8.0	pF

* Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

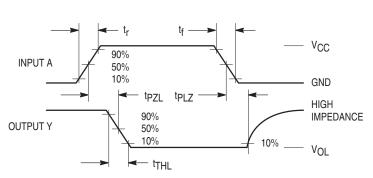
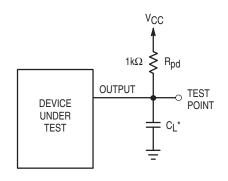
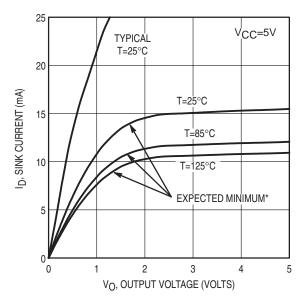


Figure 1. Switching Waveforms



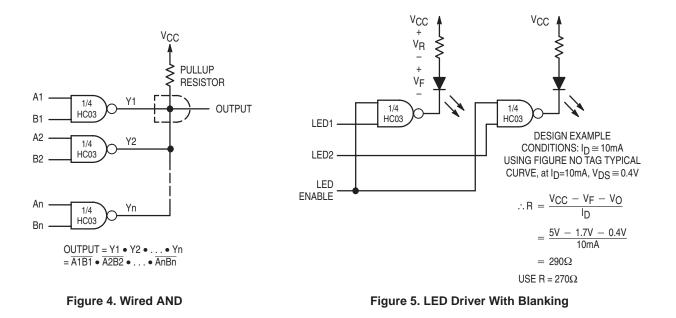
*Includes all probe and jig capacitance

Figure 2. Test Circuit



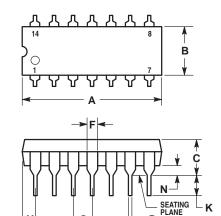
*The expected minimum curves are not guarantees, but are design aids.

Figure 3. Open–Drain Output Characteristics



PACKAGE DIMENSIONS

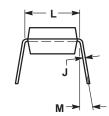
PDIP-14 **N SUFFIX** CASE 646-06 ISSUE L



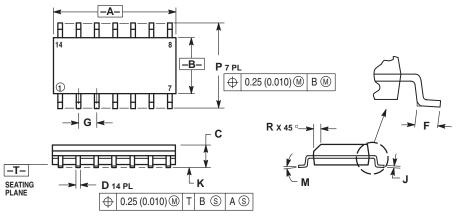
G

H

D



SOIC-14 **D SUFFIX** CASE 751A-03 **ISSUE F**



- NOTES: 1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION. 2. DIMENSION LT OCENTER OF LEADS WHEN FORMED PARALLEL. 3. DIMENSION B DOES NOT INCLUDE MOLD ELASE

 - FLASH. 4. ROUNDED CORNERS OPTIONAL

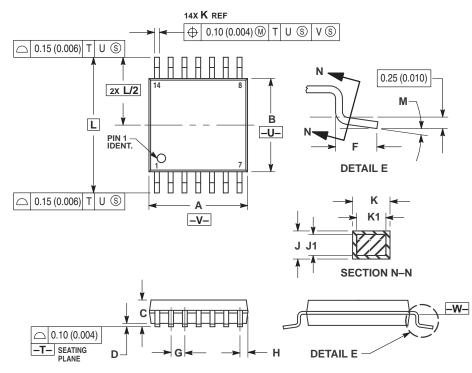
•	ROUNDED CORNERS OF HONAL.						
		INC	HES	MILLIN	IETERS		
	DIM	MIN MAX		MIN	MAX		
	Α	0.715	0.770	18.16	19.56		
	В	0.240	0.260	6.10	6.60		
	С	0.145	0.185	3.69	4.69		
	D	0.015		0.38	0.53		
	F	0.040	0.070	1.02	1.78		
	G	0.100	BSC	2.54 BSC			
	Н	l 0.052 0.095	0.095	1.32	2.41		
	J	0.008	0.015	0.20	0.38		
	Κ	0.115	0.135	2.92	3.43		
	L	0.300 BSC		7.62	BSC		
	М	0°	10°	0 °	10°		
	Ν	0.015	0.039	0.39	1.01		

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI
- I. DIMENSIONING AND TOLEHANCING PER AN Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 J. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED DIDE
- PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION OLDS NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN MAX		
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
Μ	0 °	7°	0 °	7°	
Р	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

PACKAGE DIMENSIONS

TSSOP-14 DT SUFFIX CASE 948G-01 ISSUE O



NOTES:

- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (a core) DED CODE
- 4
- OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5.
- 6.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–. 7.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40 BSC		0.252 BSC		
М	0 °	8°	0°	8°	

Notes

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Models Reliability Data	High-Perfor	mance Silicon-Gate	CMOS					
PCN Samples FAQ Part Nomenclature		IC03A is identical in h pullup resistors, th				tible with Standar	d CMOS	
Tech Support	can, therefo characterist	NAND gate has, as re, with a suitable p ic curves given in th that only requires a	ullup resistor, be unis data sheet, this of	sed in wired-A	ND applications	. Having the output	ıt	
	Features:	ut Drive Capability:	10 LSTTL Loads V	/ith Suitable P	ullup			
×	Resi • Outp • High • Oper	stor uts Directly Interfact Noise Immunity Ch ating Voltage Range	e to CMOS, NMOS aracteristic of CMC	and TTL				
	 In Co 	Input Current: 1µA ompliance With the Complexity: 28 FET			ments			
	Orderable	Parts						
	Action	Orderable Part	Short Packag Desc. Desc.		ase utline <u>Statu</u>	<u>s</u> <u>Price/Unit</u>	Pack Qty	

N/A	MC74HC03AD	Quad 2- Input NOR Gate with Drain	SOIC	14	<u>751A-03</u>	Active	\$0.160	55
N/A	MC74HC03ADR2	Tape and Reel	SOIC	14	<u>751A-03</u>	Active	\$0.160	2500
N/A	MC74HC03ADTEL	Tape and Reel	TSSOP	14	<u>948G-01</u>	Active	\$0.200	2000
N/A	MC74HC03ADTR2	Tape and Reel	TSSOP	14	<u>948G-01</u>	Active	\$0.200	2500
N/A	MC74HC03AFEL	Tape and Reel	SOIC EIAJ	14	<u>940A-03</u>	Active	\$0.160	2000
N/A	MC74HC03ADT	Quad 2- Input NAND Gate with Drain	TSSOP	14	<u>948G-01</u>	Active	\$0.200	96
N/A	MC74HC03AF	Quad 2- Input NAND Gate with Drain	SOIC EIAJ	14	<u>940A-03</u>	Active	\$0.160	50
N/A	MC74HC03AFL1	Tape and Reel	SOIC EIAJ	14	<u>940A-03</u>	LifeTime		
N/A	MC74HC03AFL2	Tape and Reel	SOIC EIAJ	14	<u>940A-03</u>	LifeTime		
N/A	MC74HC03AFR1	Tape and Reel	SOIC EIAJ	14	<u>940A-03</u>	Obsolete		

N/A	MC74HC03AFR2	Tape and Reel	SOIC EIAJ	14	<u>940A-03</u>	LifeTime		
N/A	MC74HC03AN	Quad 2- Input NAND Gate with Drain	PDIP	14	<u>646-06</u>	Active	\$0.160	500

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